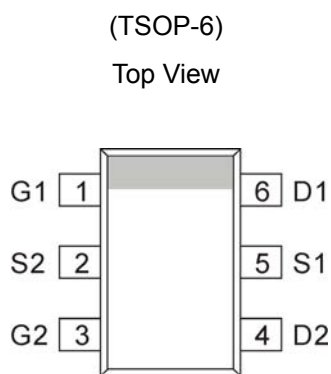


**N- and P-Channel 30V (D-S) MOSFET**

**GENERAL DESCRIPTION**

The ME3500 is the N- and P-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management and other battery powered circuits where high-side switching, and low in-line power loss are needed in a very small outline surface mount package.

**PIN CONFIGURATION**

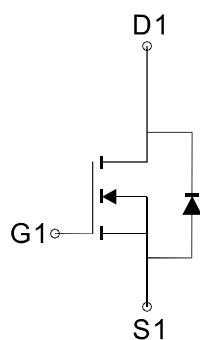


**FEATURES**

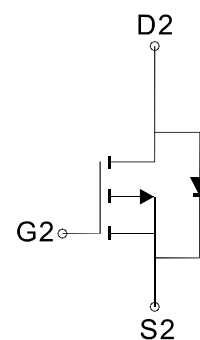
- $R_{DS(ON)} \leq 35m\Omega @ V_{GS}=10V$  (N-Ch)
- $R_{DS(ON)} \leq 52m\Omega @ V_{GS}=4.5V$  (N-Ch)
- $R_{DS(ON)} \leq 70m\Omega @ V_{GS}=-10V$  (P-Ch)
- $R_{DS(ON)} \leq 95m\Omega @ V_{GS}=-4.5V$  (P-Ch)
- Super high density cell design for extremely low  $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability

**APPLICATIONS**

- Power Management in Note book
- Portable Equipment
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter



N-Channel MOSFET



P-Channel MOSFET

Ordering Information: ME3500 (Pb-free)

ME3500-G (Green product-Halogen free)

**Absolute Maximum Ratings (TA=25°C Unless Otherwise Noted)**

Parameter	Symbol	N-Channel	P-Channel	Unit	
Drain-Source Voltage	$V_{DS}$	30	-30	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$	$\pm 20$	V	
Continuous Drain Current*	$I_D$	$T_A=25^\circ C$	4.5	-3.3	A
		$T_A=70^\circ C$	3.6	-2.7	
Pulsed Drain Current	$I_{DM}$	18	-13	A	
Maximum Power Dissipation*	$P_D$	$T_A=25^\circ C$	1.1	1.3	W
		$T_A=70^\circ C$	0.7	0.8	
Operating Junction Temperature	$T_J$	-55 to 150		°C	
Thermal Resistance-Junction to Ambient*	$R_{\theta JA}$	110	100	°C/W	

\*The device mounted on 1in2 FR4 board with 2 oz copper



**N- and P-Channel 30V (D-S) MOSFET**
**Electrical Characteristics** (TA=25°C Unless Otherwise Specified)

Symbol	Parameter	Limit	Min	Typ	Max	Unit
<b>STATIC</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250 μA	N-Ch P-Ch	1.0 -1.0	3.0 -3.0	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	N-Ch P-Ch		±100 ±100	nA
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V	N-Ch P-Ch		1 -1	μA
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>a</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> = 5A V <sub>GS</sub> =-10V, I <sub>D</sub> = -5A	N-Ch P-Ch	22 55	35 70	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> = 4A V <sub>GS</sub> =-4.5V, I <sub>D</sub> = -4A	N-Ch P-Ch	33 75	52 95	
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =1.7A, V <sub>GS</sub> =0V I <sub>S</sub> =-1.7A, V <sub>GS</sub> =0V	N-Ch P-Ch	0.8 -0.8	1.2 -1.2	V
<b>DYNAMIC</b>						
Q <sub>g</sub>	Total Gate Charge	N-Channel V <sub>DS</sub> =15V, V <sub>GS</sub> =10V, I <sub>D</sub> =5A P-Channel V <sub>DS</sub> =-15V, V <sub>GS</sub> =-10V, I <sub>D</sub> =-5A	N-Ch P-Ch	12 14	15 17	nC
Q <sub>gs</sub>	Gate-Source Charge		N-Ch P-Ch	2 4		
Q <sub>gd</sub>	Gate-Drain Charge		N-Ch P-Ch	2.5 3		
C <sub>iss</sub>	Input Capacitance	N-Channel V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz P-Channel V <sub>DS</sub> =-15V, V <sub>GS</sub> =0V, f=1MHz	N-Ch P-Ch	360 450	420 490	pF
C <sub>oss</sub>	Output Capacitance		N-Ch P-Ch	70 70		
C <sub>rss</sub>	Reverse Transfer Capacitance		N-Ch P-Ch	17 20		
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	N-Ch P-Ch	0.5 3.5		Ω
t <sub>d(on)</sub>	Turn-On Delay Time	N-Channel V <sub>DD</sub> =15V, R <sub>L</sub> =15Ω I <sub>D</sub> =1A, V <sub>GEN</sub> =10V, R <sub>G</sub> =6Ω  P-Channel V <sub>DD</sub> =-15V, R <sub>L</sub> =15Ω I <sub>D</sub> =-1A, V <sub>GEN</sub> =-10V, R <sub>G</sub> =6Ω	N-Ch P-Ch	9.3 27	13 33	ns
t <sub>r</sub>	Turn-On Rise Time		N-Ch P-Ch	14 11	18 15	
t <sub>d(off)</sub>	Turn-Off Delay Time		N-Ch P-Ch	32 40	41 52	
t <sub>f</sub>	Turn-Off Fall Time		N-Ch P-Ch	3.2 4	5 6	

Note: a. Pulse test: pulse width ≤ 300μs, duty cycle ≤ 2%

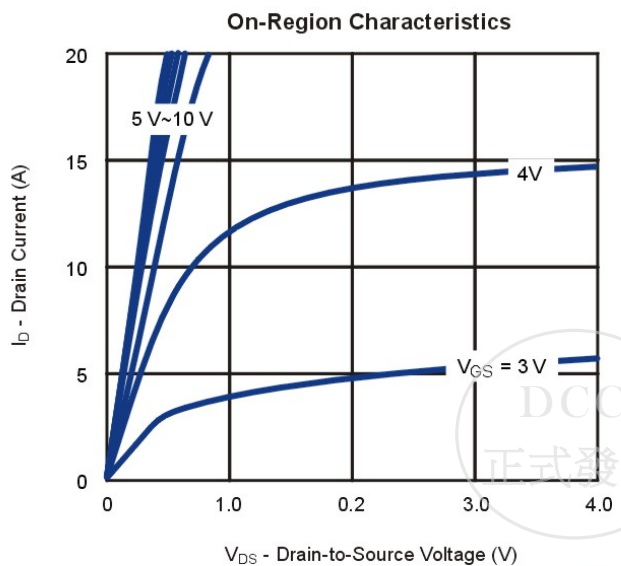
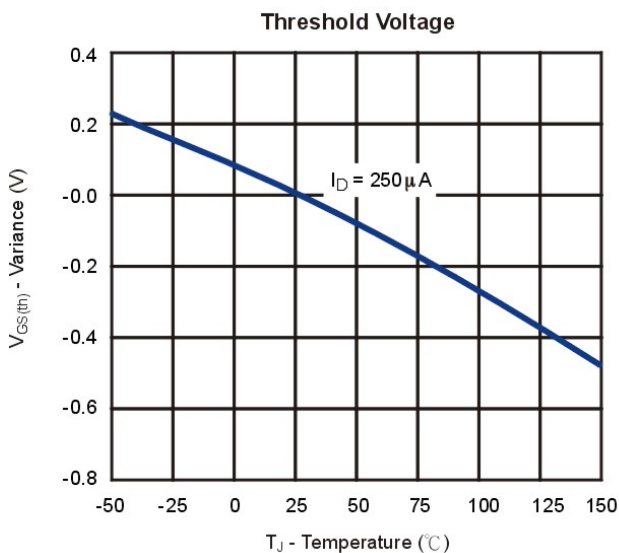
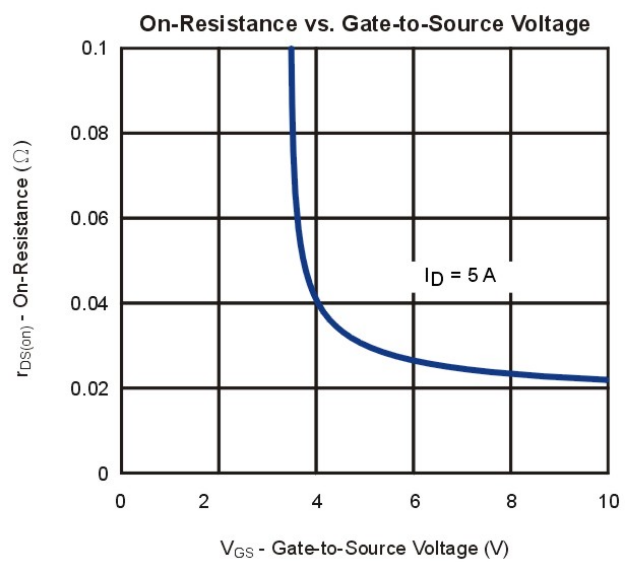
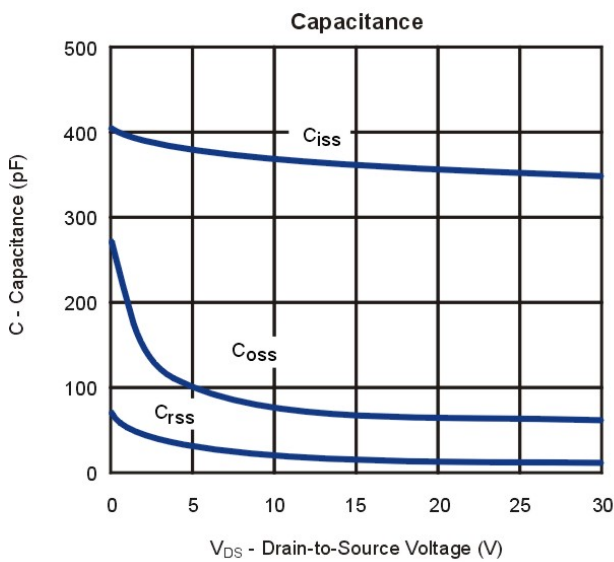
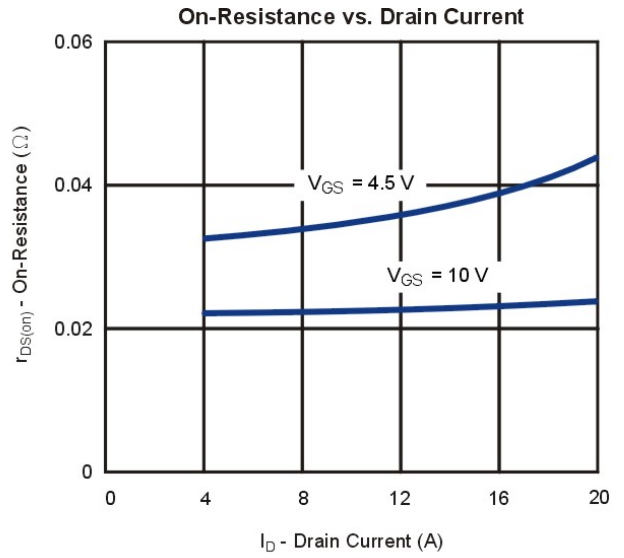
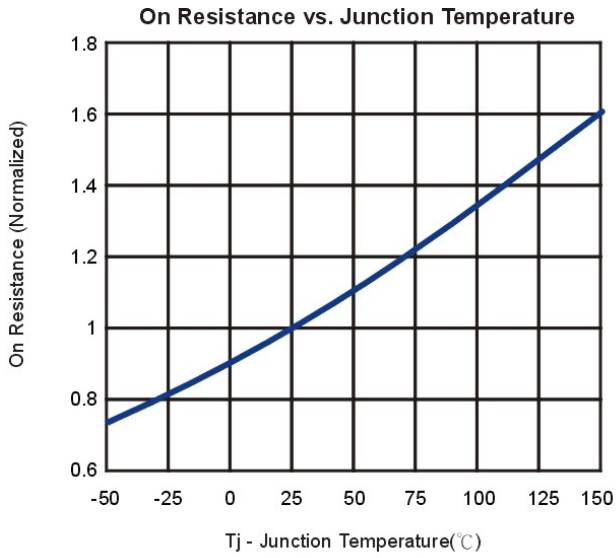
b. Matsuki Electric/ Force mos reserves the right to improve product design, functions and reliability without notice.



**N- and P-Channel 30V (D-S) MOSFET**

**Typical Characteristics (T<sub>J</sub> = 25°C Noted)**

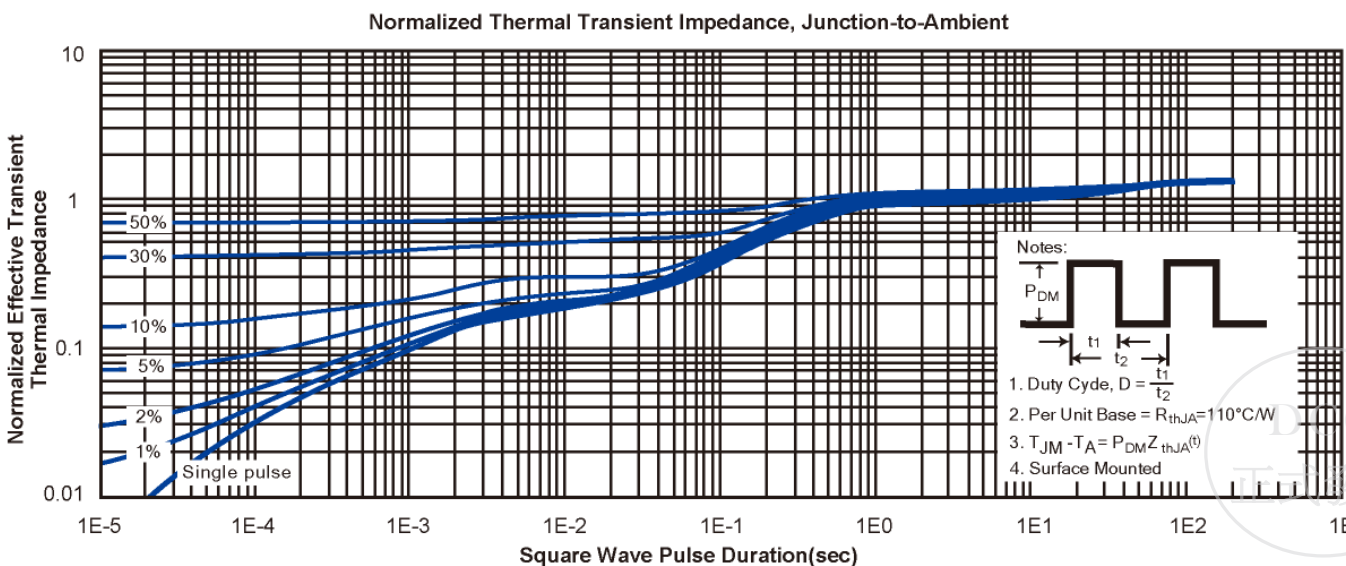
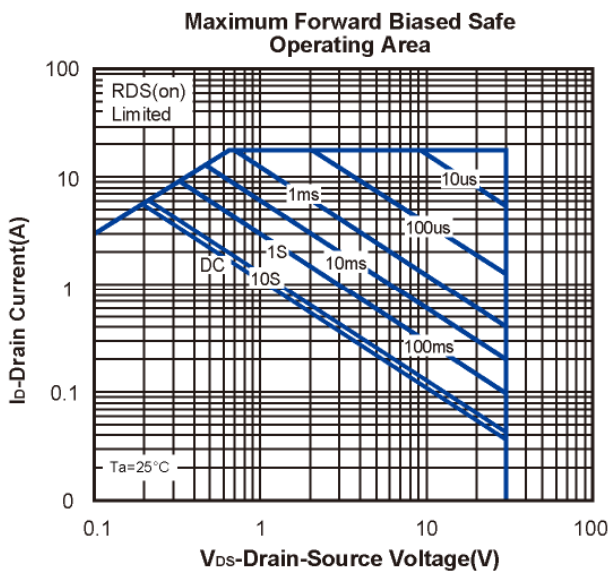
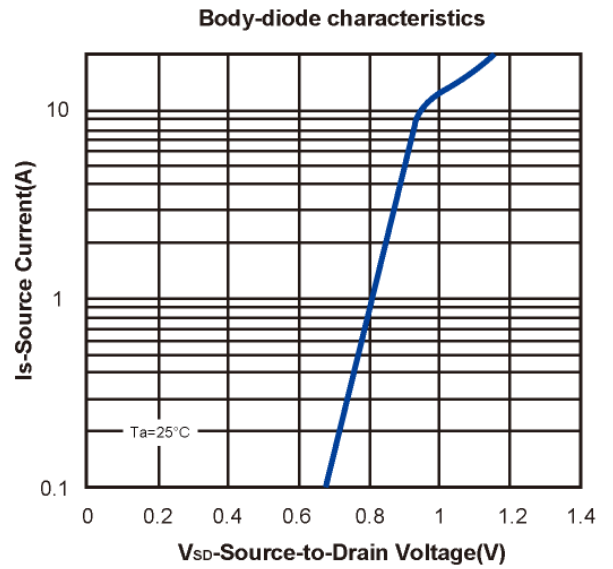
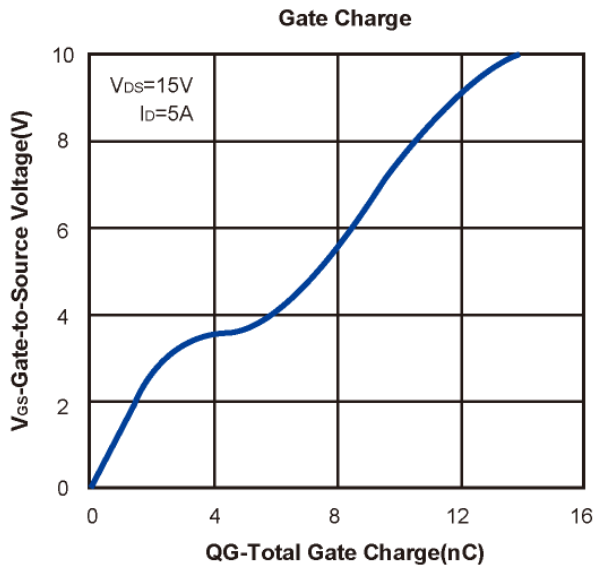
**N-CHANNEL**



**N- and P-Channel 30V (D-S) MOSFET**

**Typical Characteristics (T<sub>J</sub> =25°C Noted)**

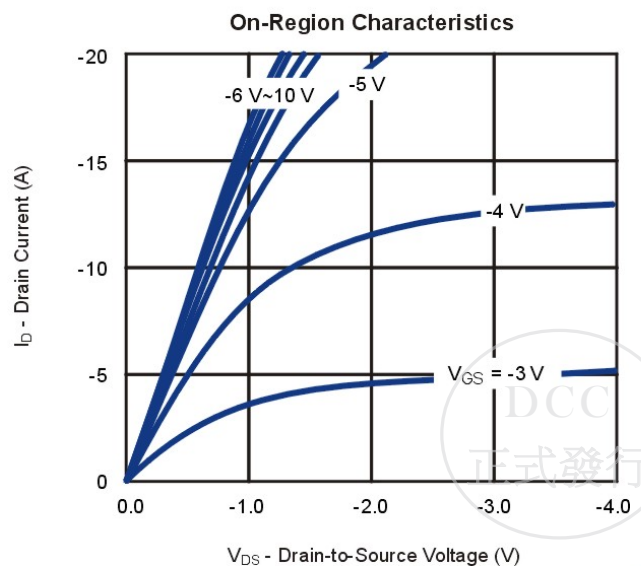
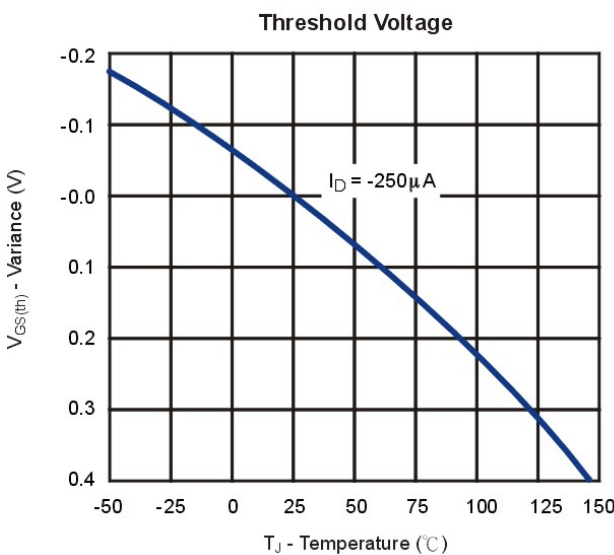
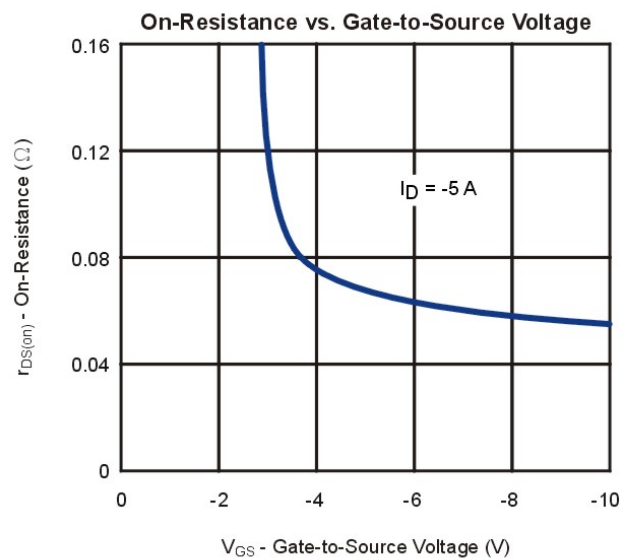
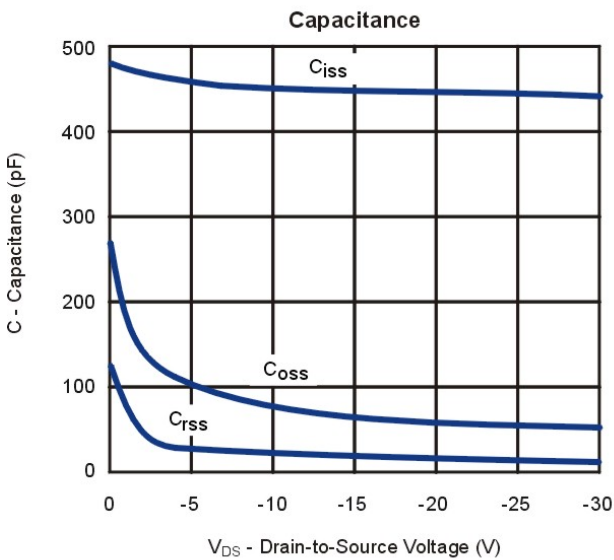
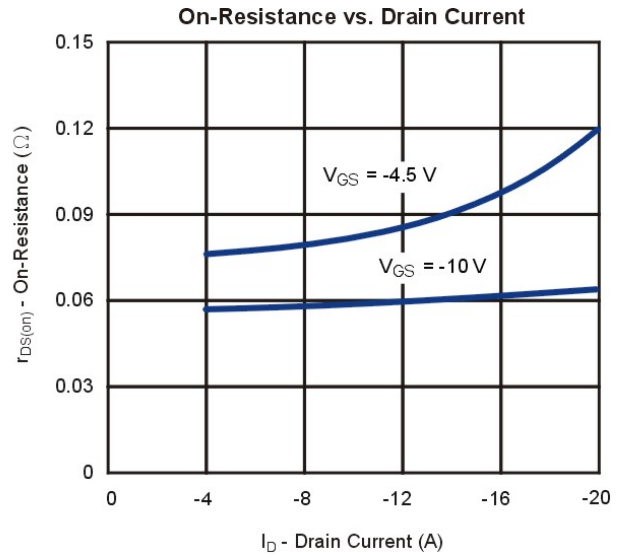
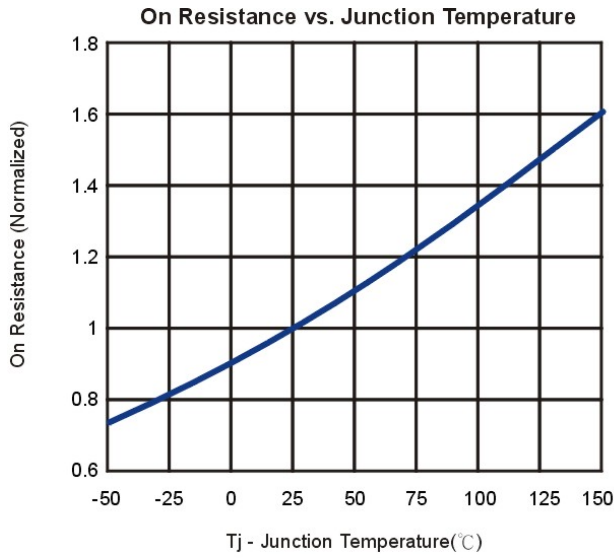
**N-CHANNEL**



**N- and P-Channel 30V (D-S) MOSFET**

**Typical Characteristics (T<sub>J</sub> = 25°C Noted)**

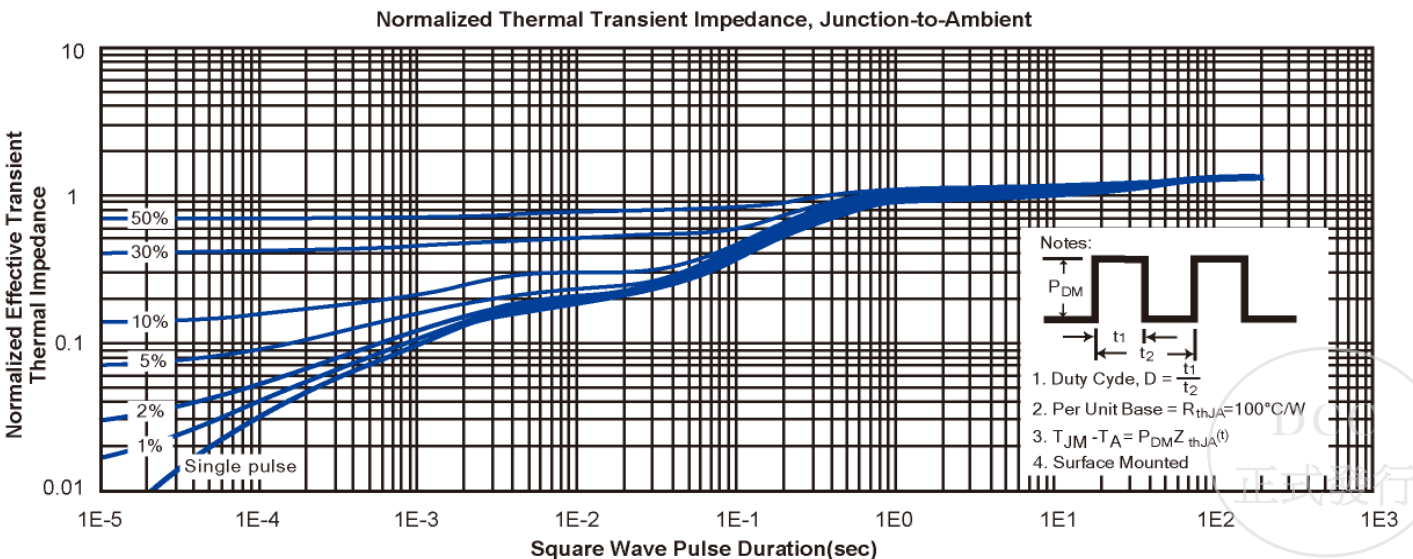
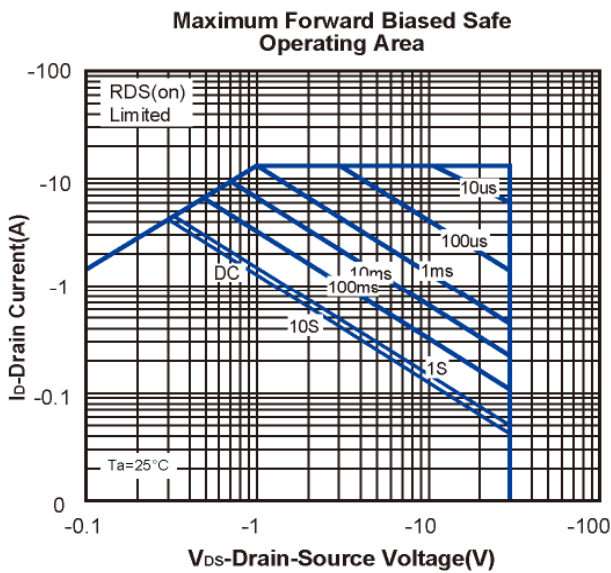
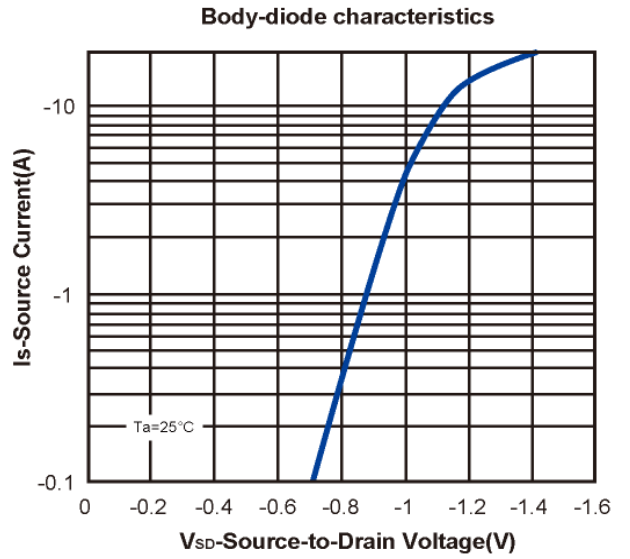
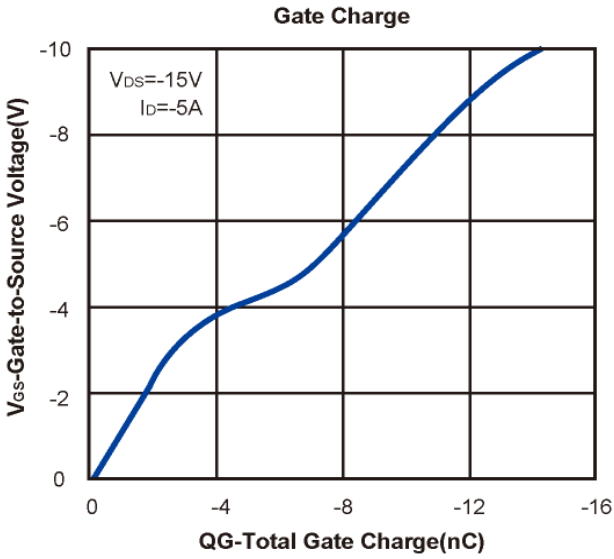
**P-CHANNEL**



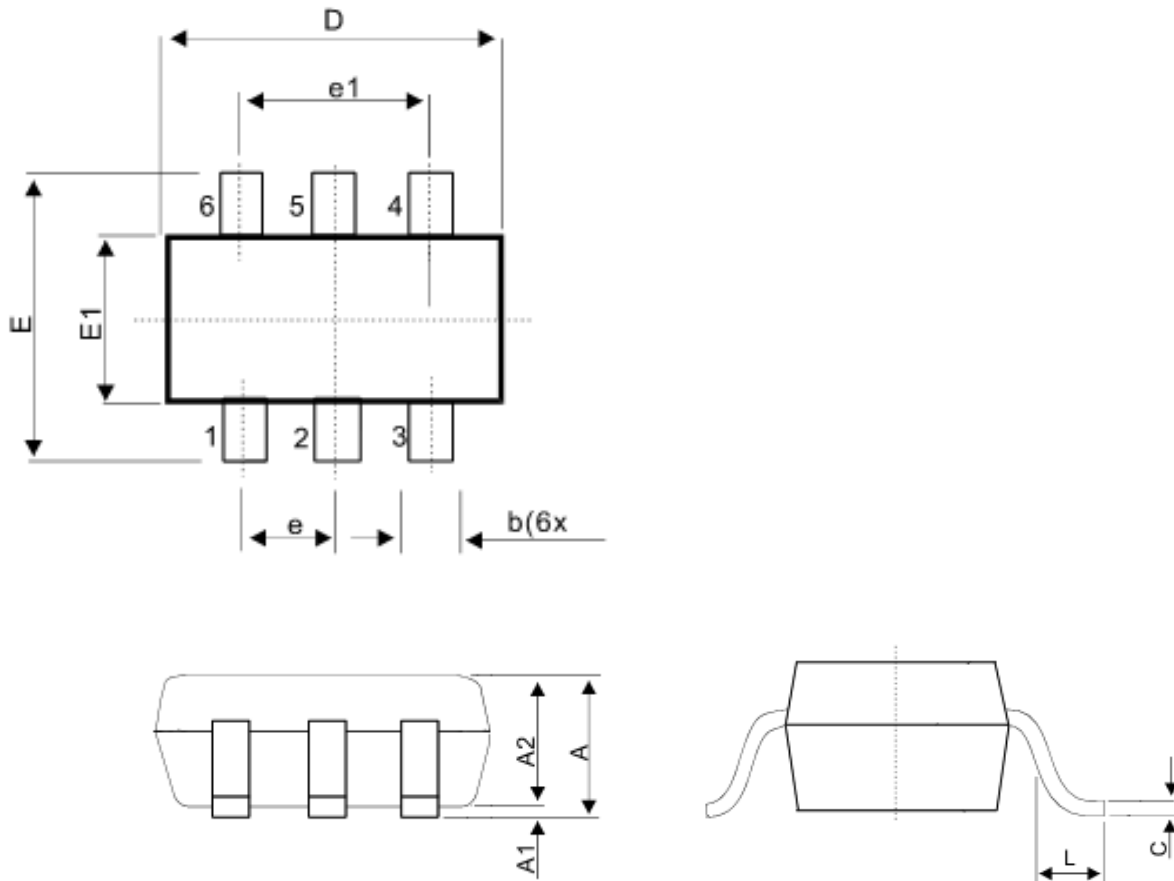


**N- and P-Channel 30V (D-S) MOSFET**  
**Typical Characteristics (T<sub>J</sub> =25°C Noted)**

**P-CHANNEL**



**TSOP-6 Package Outline**



SYMBOL	MILLIMETERS (mm)	
	MIN	MAX
A	0.90	1.20
A1	0.01	0.10
A2	0.90	1.15
b	0.25	0.50
C	0.10	0.20
D	2.80	3.10
E	2.60	3.00
E1	1.50	1.70
e	0.95 BSC	
e1	1.90 BSC	
L	0.30	0.60

